SDLS036 - DECEMBER 1983 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

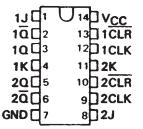
description

The '107 contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '107 is a positive pulse-triggered flip-flop. The J-K input data is loaded into the master while the clock is high and transferred to the slave and the outputs on the high-to-low clock transistion. For these devices the J and K inputs must be stable while the clock is high.

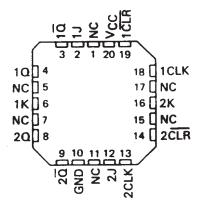
The 'LS107A contain two independent negative-edge-triggered flip-flops. The J and K inputs must be stable prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Q output low and the $\overline{\mathbf{Q}}$ output high.

The SN54107 and the SN54LS107A are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN74107 and the SN74LS107A are characterized for operation from 0 °C to 70 °C.

SN54107, SN54LS107A . . . J PACKAGE SN74107 . . . N PACKAGE SN74LS107A . . . D OR N PACKAGE (TOP VIEW)



SN54LS107A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

'107
FUNCTION TABLE

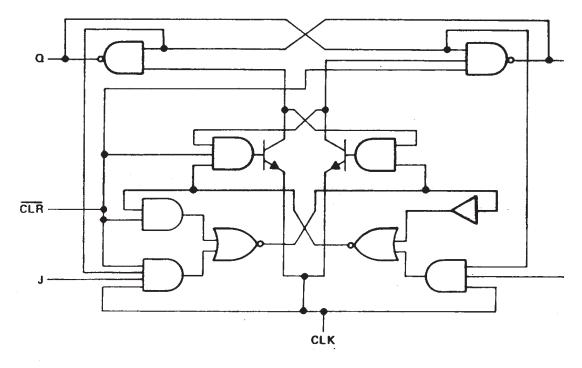
[INPU	TS		OUTF	UTS		
CLR	CLK	J	Κ	a	ā		
L	×	Х	Х	L	Н		
н	ır	L	L	α_0	\bar{a}_0		
H	T	Н	L	н	L		
Н	. 1	i.	н	L	Н		
н	л	Н	н	TOGGLE			

'LS 107A FUNCTION TABLE

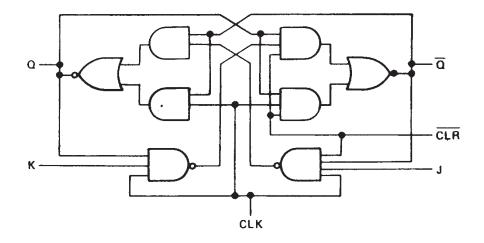
	INPU	TS		OUT	UTS
CLR	CLK	J	К	α	₫
L	×	Х	Х	L	Н
н	1	L	L	σ_0	\bar{a}_0
н	4	Н	L	н	L
н	1	L	Н	L	Н
н⊦	4	H.	н	TOG	GLE
н	Н	Х	×	△0	\overline{a}_0



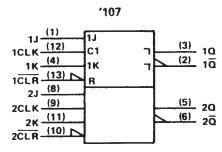
logic diagrams (positive logic)

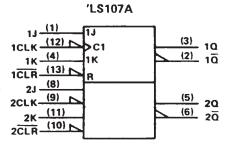


'LS107A



logic symbols†



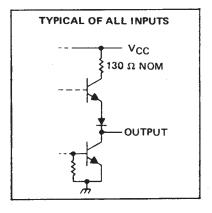


[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, and N packages.

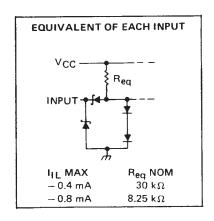
schematic of inputs and outputs

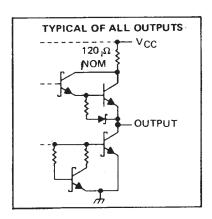
I₁L MAX R_{eq} NOM - 1.6 mA 4 kΩ - 3.2 mA 2 kΩ





'LS107A





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

5.5 V
- 55°C to 125°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN54107				SN7410)7	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			8.0	V
ЮН	High-level output current				- 0.4			- 0.4	mA
IOL	Low-level output current				16			16	mA
		CLK high	20			20			
tw	Pulse duration	CLK low	47			47			ns
		CLR low	25			25			
t _{su}	Input setup time before CLK1		0			0			ns
t _h	Input hold time-data after CLK1		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAG	RAMETER		TEST CONDITI	ovet		SN5410	7		SN7410	7	
100	MANIETER		TEST CONDITT	ON2.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
v_{IK}		V _{CC} = MIN,	I ₁ = - 12 mA				- 1.5			– 1.5	V
V _{OH}		V _{CC} = MIN,	V _{IH} = 2 V,	V _{IL} = 0.8 V,	2.4	3.4		2.4	3.4		V
VOL		V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V,	V _{1L} = 0.8 V,		0.2	0.4		0.2	0.4	٧
t _l		V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
1	J or K	\/ - M AX	V ₁ = 2.4 V				40			40	
ΊΗ	All other	V _{CC} = MAX,	V = 2.4 V				80			80	μΑ
1	J or K	VMAY	V =0.4 V				- 1.6			- 1.6	
ILF	All other	V _{CC} = MAX,	V ₁ = 0.4 V				- 3.2			- 3.2	mA
los §		V _{CC} = MAX			- 20		- 57	- 18		- 57	mA
lcc1		V _{CC} = MAX,	See Note 2			10	20		10	20	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				15	20		MHz
[†] PLH	CLR	ā			16	25	ns
^t PHL	CLA	α	$R_{\perp} = 400 \Omega$, $C_{\perp} = 15 pF$		25	40	ns
^t PLH	CLK	Q or $\overline{\Omega}$			16	25	ns
^t PHL	CLK	d ord			25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_{A} = 25° C.

[§]Not more than one output should be shorted at a time.

[¶]Average per flip-flop.

recommended operating conditions

			S	N54LS1	07A	S	N74LS1	07A	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
V _C C	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			8.0	V
¹ ОН	High-level output current				- 0.4			- 0.4	mA
†OL	Low-level output current				4			8	mA
fclock	Clock frequency		0		30	0		30	MHz
	Dulan dunain	CLK high	20			20			
tw	Pulse duration	CLR low	25		;	25		,	ns
	0	data high or low	20			20			
^t su	Setup time before CLK #	CLR inactive	25			25		-	ns
th	Hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		_	FOT COMPLETO	uct	18	V54LS10)7A	SN	174LS10)7A	UNIT
PA	RAMETER] 	EST CONDITION	V S'	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNII
VIK		V _{CC} = MIN,	I _I = - 18 mA				- 1.5			– 1.5	V
Vон		V _{CC} = MIN, I _{OH} = 0.4 mA	V _{IH} = 2 V,	VIL = MAX,	2.5	3.4		2.7	3.4		٧
\/_		V _{CC} = MIN, I _{OL} = 4 mA	VIL = MAX,	V _{IH} = 2 V,		0.25	0.4		0.25	0.4	>
VOL		V _{CC} = MIN, I _{OL} = 8 mA	VIL = MAX,	V _{IH} = 2 V,					0.35	0.5	
	J or K						0.1			0.1	
4	CLR	V _{CC} = MAX,	V ₁ = 7 V				0.3			0.3	mA
	CLK						0.4			0.4	
	J or K						20			20	
ЧН	CLR	V _{CC} = MAX,	V1 = 2.7 V				60			60	μΑ
	CLK						80			80	
	J or K		V = 0.4.V				- 0.4			- 0.4	mA
HL	CLR or CLK	V _{CC} = MAX,	V ₁ = 0.4 V				- 0.8			0.8	100
los §		V _{CC} = MAX,	See Note 4		20		- 100	- 20		- 100	mA
Icc (Total)	V _{CC} = MAX,	See Note 2			4	6		4	6	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COM	NDITIONS	MIN	TYP	MAX	UNIT
fmax			,		30	45		MHz
tPLH		^ =	$R_L = 2 k\Omega$,	C _L = 15 pF		15	20	ns
tPHL	CLR or CLK	Q or Q				15	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \overline{Q} , outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with VO = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00203BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00203BCA	Samples
M38510/00203BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00203BCA	Samples
M38510/00203BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00203BCA	Samples
SN54107J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54107J	Samples
SN54107J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54107J	Samples
SN74LS107AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS107A	Samples
SN74LS107AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS107A	Samples
SN74LS107AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS107AN	Samples
SN74LS107AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS107AN	Samples
SN74LS107ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS107A	Samples
SN74LS107ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS107A	Samples
SNJ54107J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54107J	Samples
SNJ54107J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54107J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS**: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".



PACKAGE OPTION ADDENDUM

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RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS107ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS107ANSR	so	NS	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LS107AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS107AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS107AN	N	PDIP	14	25	506	13.97	11230	4.32

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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